

INITIAL INFORMATION DATA SHEET

APPLICATION INFORMATION

Application Type:: Regular
Subject Matter:: Utility
Title:: High Performance FlipChip Package
That Incorporates Heat Removal With
Minimal Thermal Mismatch
Docket Number:: X-901 US
Request for Early Pub?:: No
Request for Non-Pub?:: Yes
Total Drawing Sheets:: 3
Small Entity?:: No

INVENTOR INFORMATION

Inventor Authority Type:: Inventor
Primary Citizenship Ctry:: US
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Inventor Authority Type:: Inventor
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Given Name:: Lan H.
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